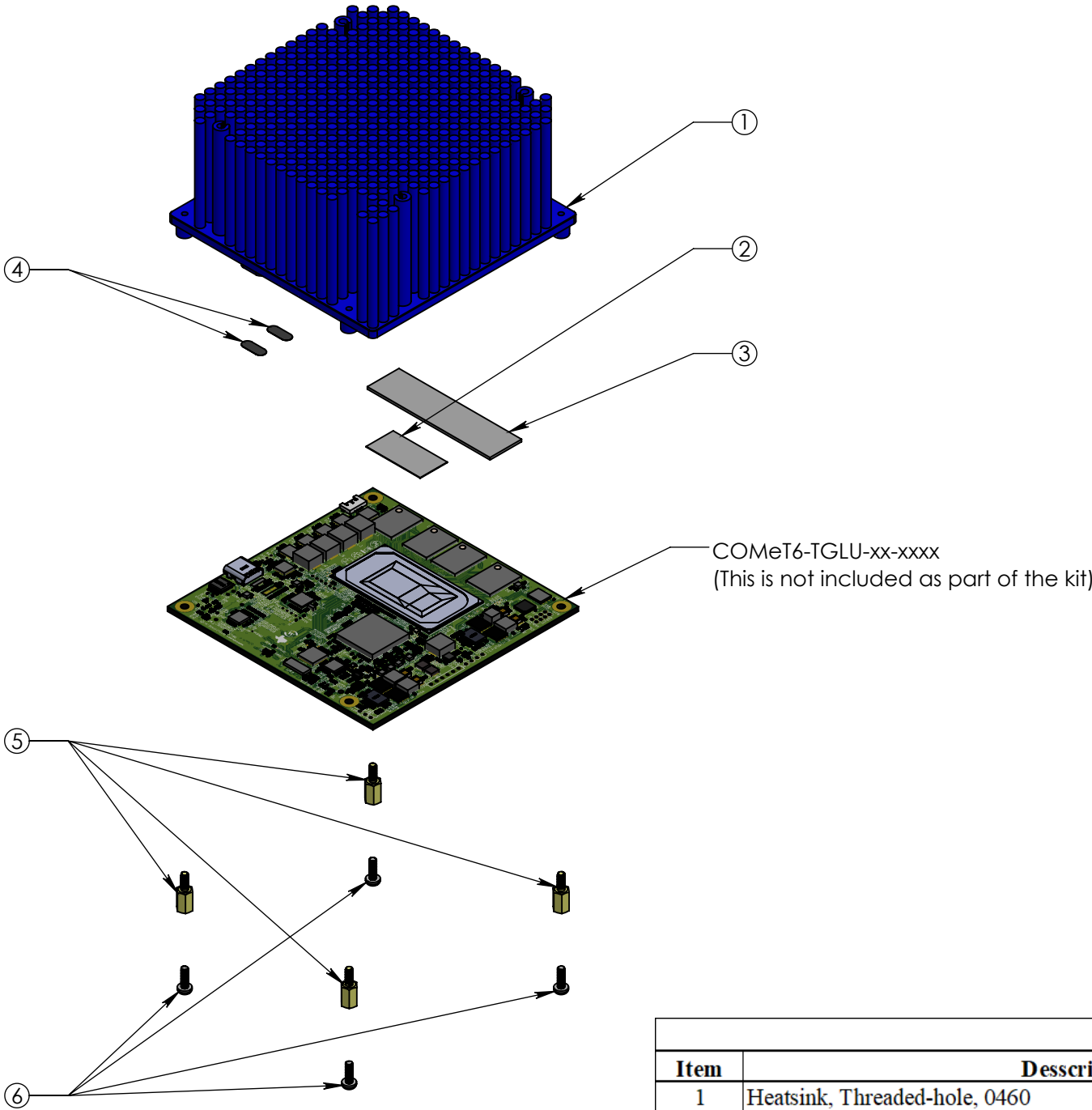


REVISION INFORMATION			
REV.	DESCRIPTION	DATE	NAME
A	NEW DRAWING, Updated BOM	05/09/2023	V. TRAN



NOTE:  
1. BOM Items will be packed into its final packaging (item 7) as a kit.  
2. Thermal Interface Materials, and Mylar Tapes will be installed onto Heatsink.  
3. All hardware will be packed with a plastic bag inside the final packaging box.  
4. Shipping box specification as following:  
Material: Wood Free Paper  
LBKP: 60%-70%  
NBKP: 15%-20%  
Starch: 1%-2%  
CaCO3: 15%-20%  
Printed WinSystems shipping label as below



2890 112th Street  
Grand Prairie, Texas 75050  
Tel: 817-274-7553  
www.winsystems.com

Embed Success in Every Product



COMET6-460-HTSK-1 (Heatsink, Threaded)					
Item	Desscription	WinSystems P/N	WinSystems Repair P/N	Manufacturer P/N	Quantity
1	Heatsink, Threaded-hole, 0460	G502-0460-301A.1	G502-0460-301A.1	G502-0460-301A.1	1
2	CPU Thermal Interface Material		G502-0109-009A	F002-00819	1
3	DDR Thermal Interface Material		G502-0109-010A	F002-00820	1
4	Mylar Tape, thickness <0.10mm		500-3007-403A	F002-00822	2
5	Hex stand-off, M2.5x0.45 x 8mm		G527-030D-400	F003-00183	4
6	Machine screw, M2.5x0.45 x 8mm SS Phillip Pan-head		G527-000D-401	F001-00507	4
7	White shipping box with foam inserts, 125x125x62mm (est.)		975-0100-018A	HMFH9550-16	1